

Product Description

Shin-Etsu's X-23-7868-2D thermal interface grease is a solvent-diluted grease that exhibits exceptional thermal conductivity after the added solvent has evaporated. Due to the dilution of X-23-7868-2D, it is easy to handle while still maintaining excellent thermal conductivity.

Product Features

- Exceptional thermal conductivity
- Solvent diluted
- Ease of use

Typical Applications

- CPUs
- MPUs
- Semiconductor elements and heat sinks requiring high thermal conductivity

Typical Properties

Type	Thermal Grease
One/Two Component	One
Low Molecular Weight Siloxane Stripped?	Y
Color	Gray
Density @ 23C (g/cm ³)	2.50
Viscosity (Pa·s)	100
Thermal Conductivity (W/m·K)	6.20
Thermal Resistance (mm ² ·K/W)	7
% Volatile Content	2.70
Usable Temp. Range (C)	-50 to +120
Bond Line Thickness (µm)	25

Note: Values are not for specification purposes.

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